



Material Composition Sheet

Product: GS9064-CTD
 Package Type: SOIC-16N taped (250/reel)
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		1.96	Al	0.01	0.51	5102
			Si	1.95	99.48	994898
			Sub-total:	1.96	99.99	1000000
Die Attach	84-1 LMISR4	0.16	Aromatic Amine	0.01	6.25	62500
			Epoxy Resin	0.03	18.75	187500
			Silver	0.12	75.00	750000
			Sub-total:	0.16	100.00	1000000
Lead Finish External		1.57	Pb	0.39	24.84	248408
			Sn	1.18	75.15	751592
			Sub-total:	1.57	99.99	1000000
Lead Finish Internal		0.30	Ag	0.30	100.00	1000000
			Sub-total:	0.30	100.00	1000000
Leadframe	Olin 194FH	54.25	Cu	52.89	97.49	974931
			Fe	1.27	2.34	23410
			P	0.02	0.03	369
			Zn	0.07	0.12	1290
			Sub-total:	54.25	99.98	1000000
Marking Ink	Wieder W238	0.01		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME G6300H	92.01	Antimony Trioxide	2.76	2.99	29997
			BrominatedEpoxyResin	1.84	1.99	19998
			Carbon Black	0.28	0.30	3043
			Epoxy Cresol Novolac	14.72	15.99	159983
			Phenol/Novolac resin	5.24	5.69	56950
			Silica Fused	67.17	73.00	730029
			Sub-total:	92.01	99.96	1000000
Wires	SGA3	0.41	Au	0.41	100.00	1000000
			Sub-total:	0.41	100.00	1000000
Total:		150.67				

GENNUM CORPORATION

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